

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	
<b>Filing Date:</b>	
<b>Title of Invention:</b>	SOLDER COMPOSITION AND METHOD OF BUMP FORMATION THEREWITH
<b>First Named Inventor:</b>	Isao SAKAMOTO
<b>Filer:</b>	Leslie J. Paperner/Ayako Asada
<b>Attorney Docket Number:</b>	P30245

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
National Stage Fee	1631	1	300	300
Natl Stage Search Fee - Report provided	1642	1	400	400
National Stage Exam - all other cases	1633	1	200	200

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
	<b>Total in USD (\$)</b>			<b>900</b>